AGM-005

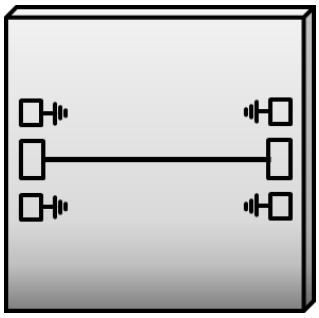
GaAs MMIC Thru Line

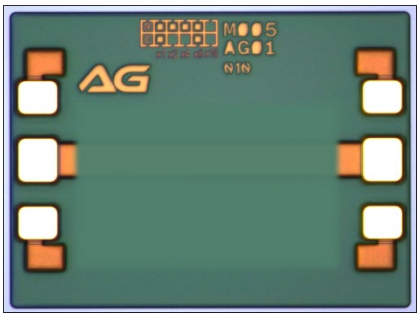
Typical Applications

- Communication Systems
- Point to Point Radio
- Fiber Optics
- Test Equipment
- Wideband Military & Space

Features

- Frequency Range: DC – 40GHz
- Passband Loss: 0.2dB @ 20GHz
- 50Ω Matched DC coupled RF Ports
- Size matches the LPF and BPF MMIC die
- Chip Size: 1.00 x 0.750 x 0.1 mm^2



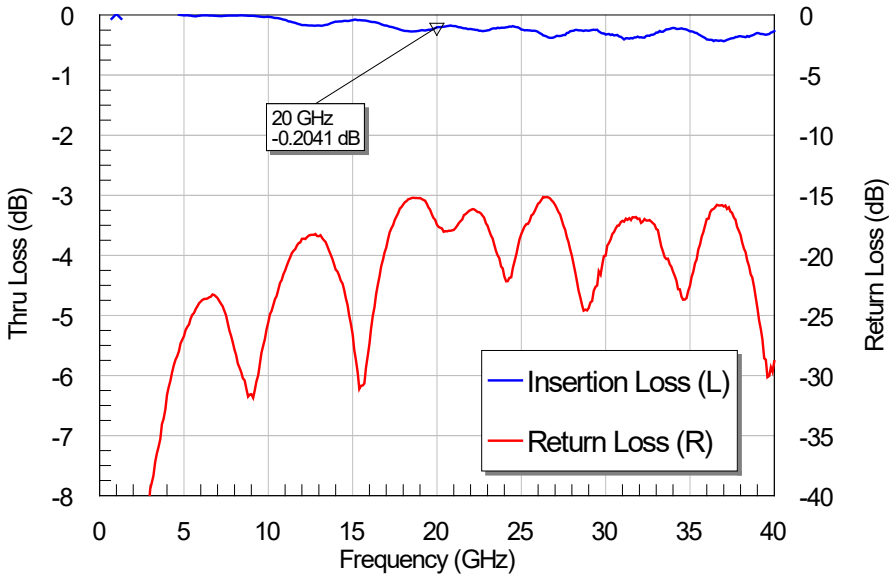


Parameter	Units	Minimum	Typical	Maximum
Frequency	GHz	DC		40
Passband Loss	dB			0.26
Passband Return Loss	dB			15
Package Type			Die	

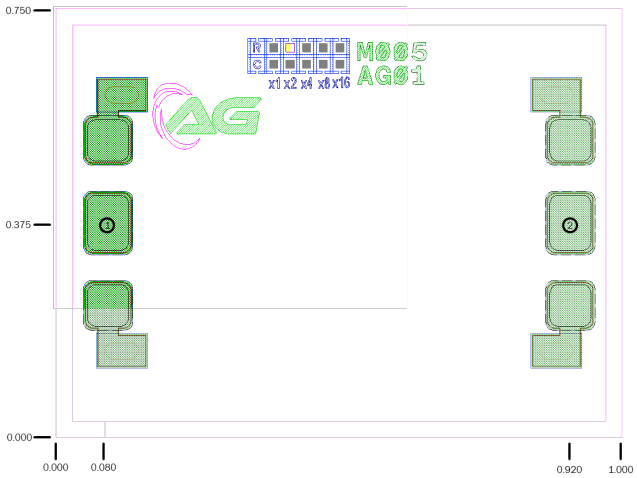
Thru Lines - Die

Performance Graphs

Gain and Return Loss



Outline Drawing (dimensions in mm)

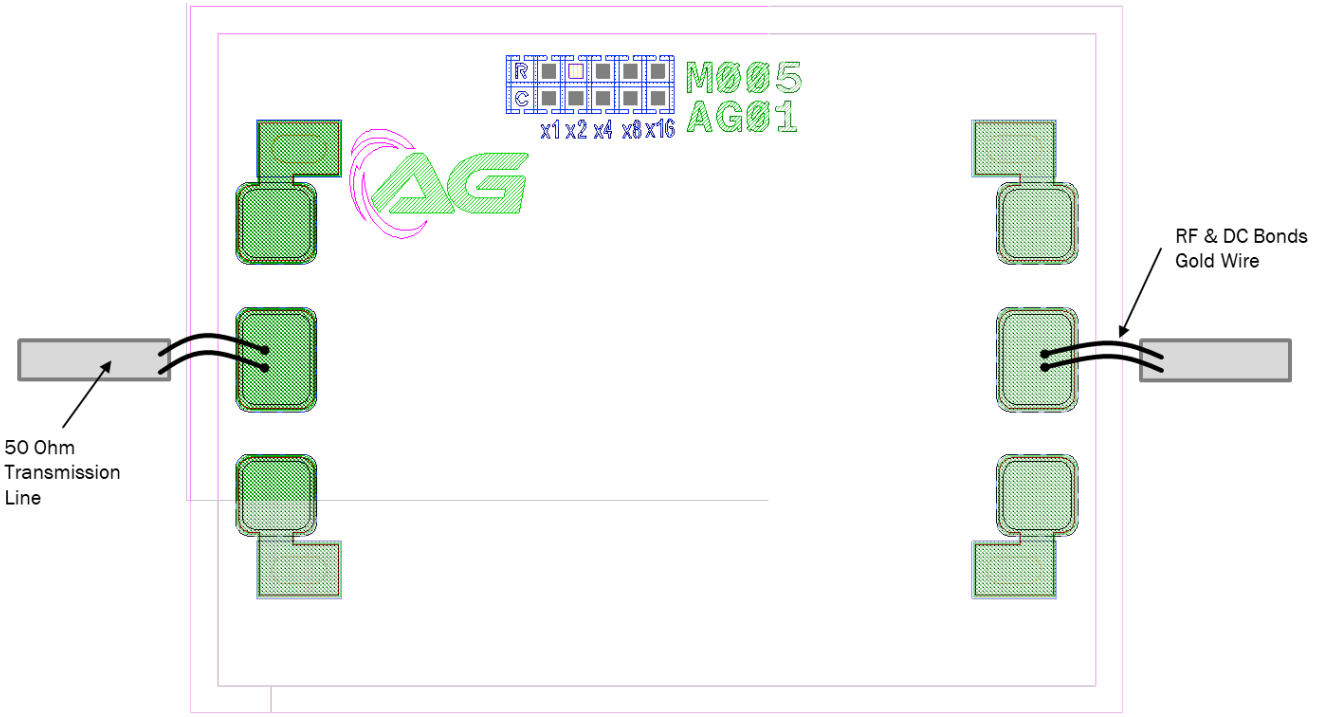


Pad Descriptions

Pad	Function	Pad Size	Description
1	RFIN	75x100µm	DC coupled 50Ω Matched
2	RFOUT	75x100µm	DC coupled 50Ω Matched
Die Bottom	GND	Backside	Epoxy/Solder to Baseplate

Absolute Maximum Ratings

Drain Bias Voltage (VDD)	No Bias
RF Input Power (RFIN)	+20dBm*
Channel Temperature	150°C
Storage Temperature	-65 to 150°C
Operating Temperature	-55 to 85°C



Assembly Notes:

1. Die Thickness is 100µm
2. Backside and Bondpad metallization: 4µm gold
3. Silver Epoxy or AuSn Eutectic attach MMIC

Die Packaging Information

- GP-8 (Gel-Pak)